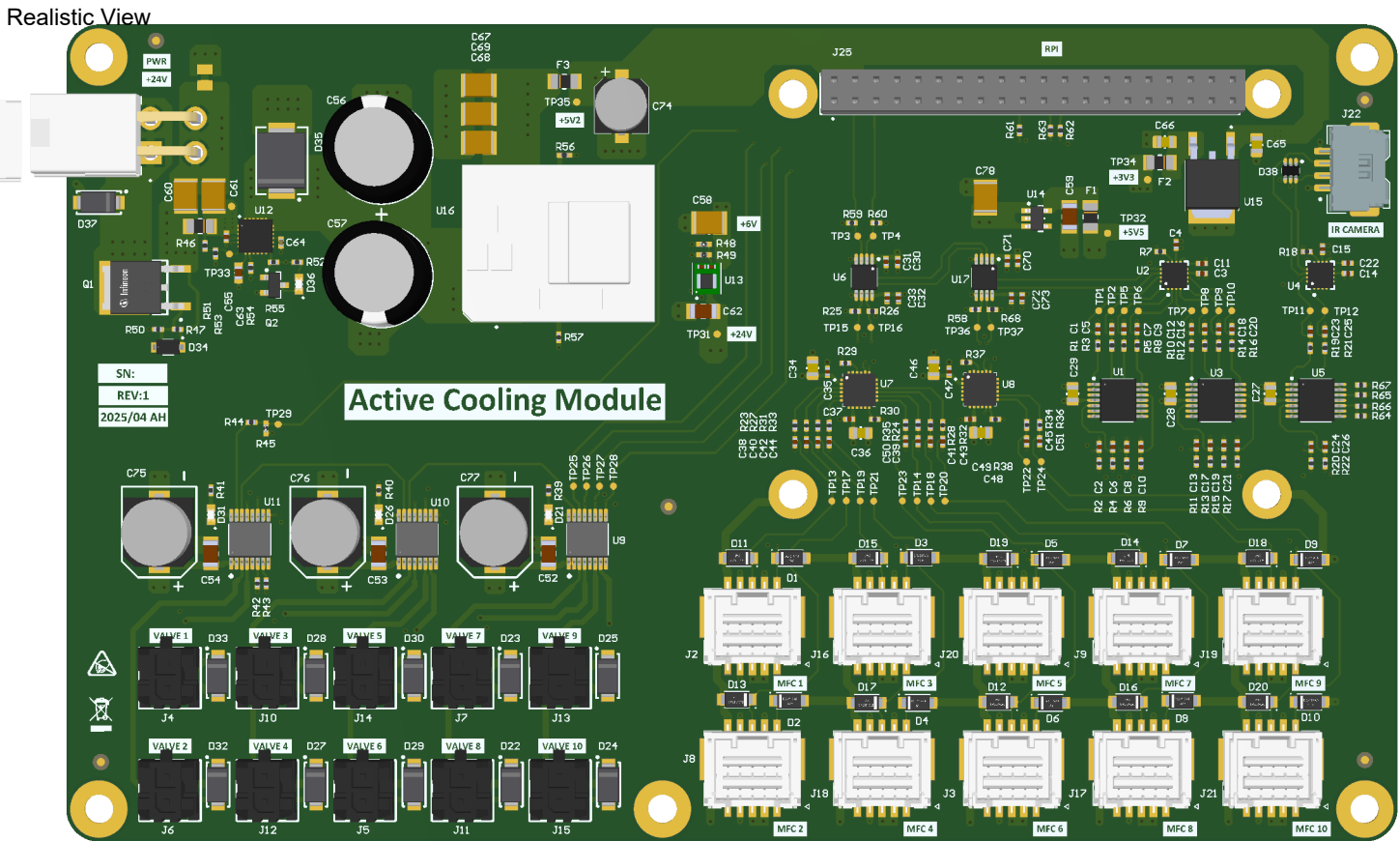
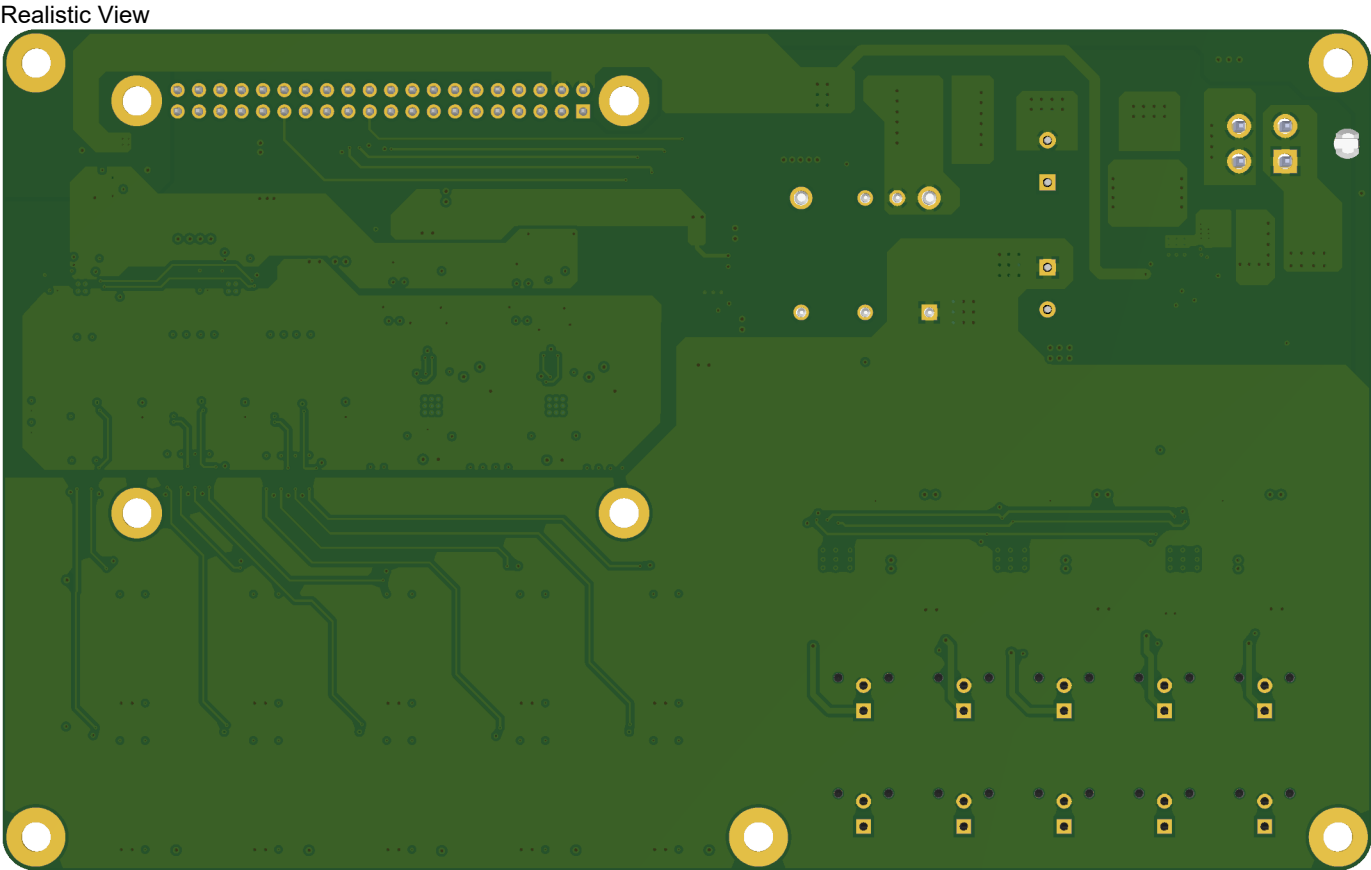


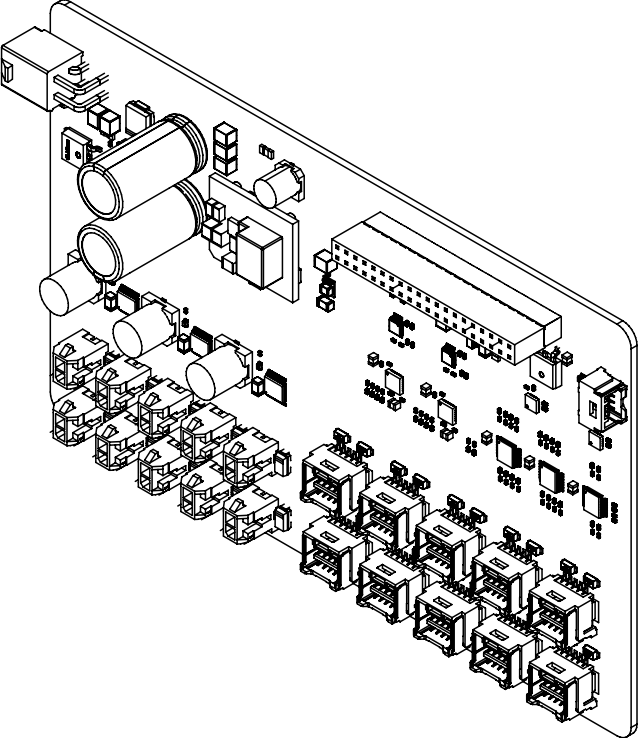
Realistic View



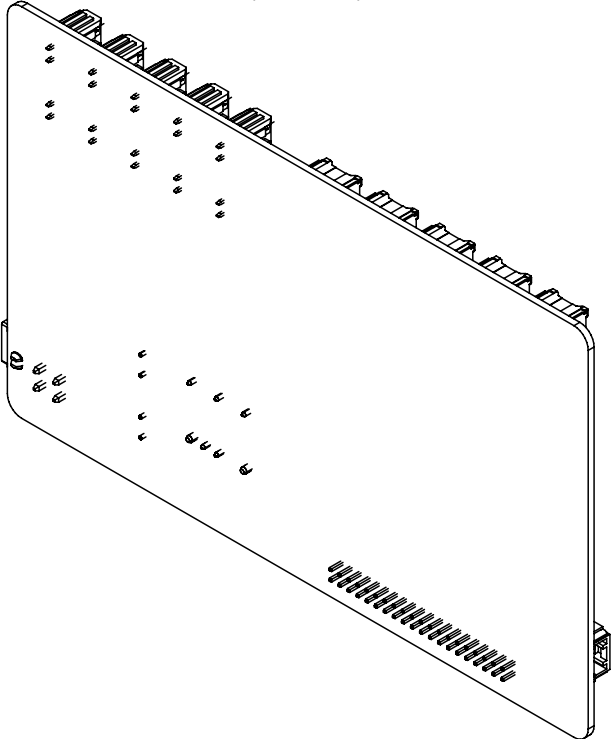
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Dimensions

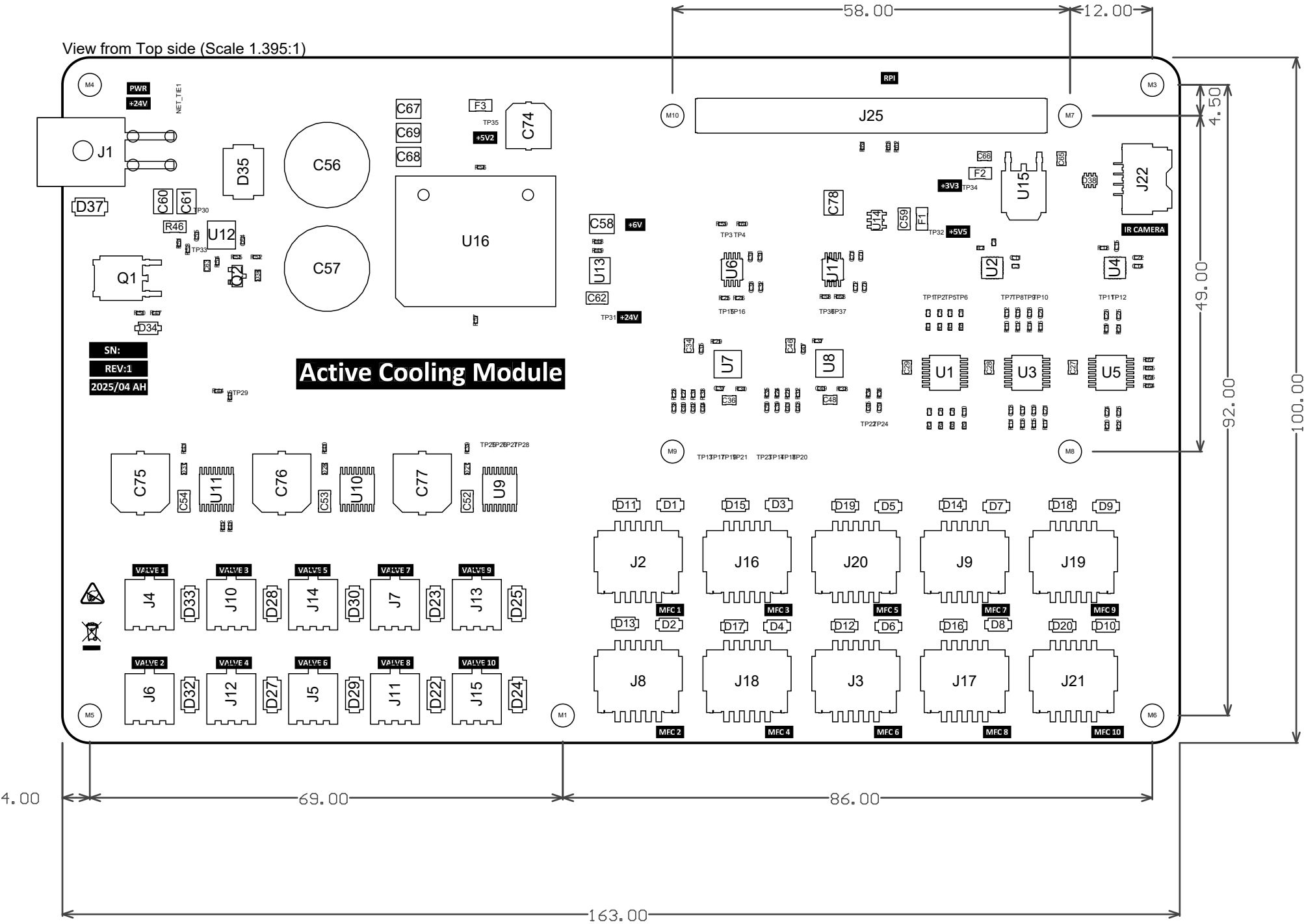
View from Top side (Scale 2:3)



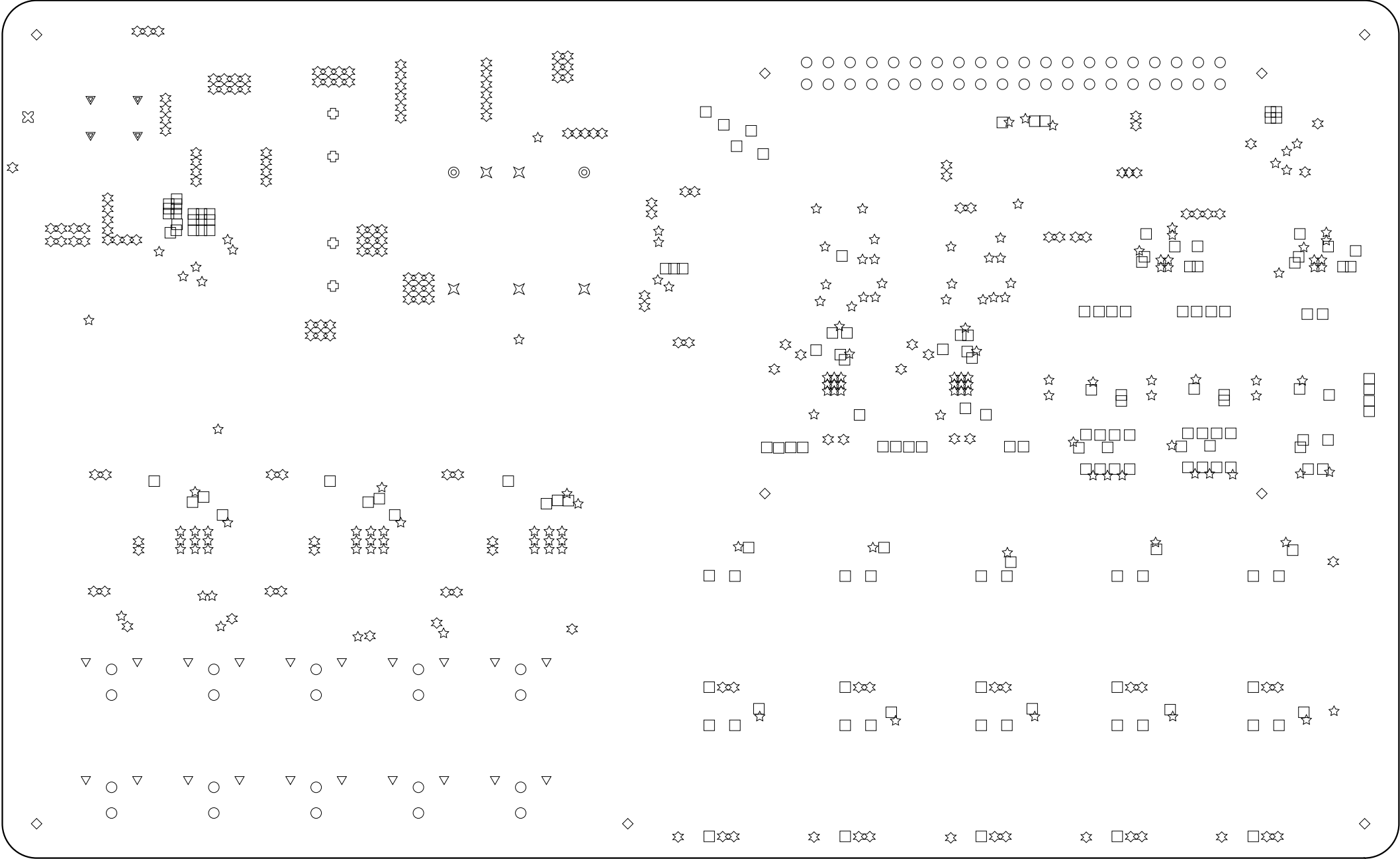
View from Bottom side (Scale 2:3)




View from Top side (Scale 1.395:1)



Drill Drawing

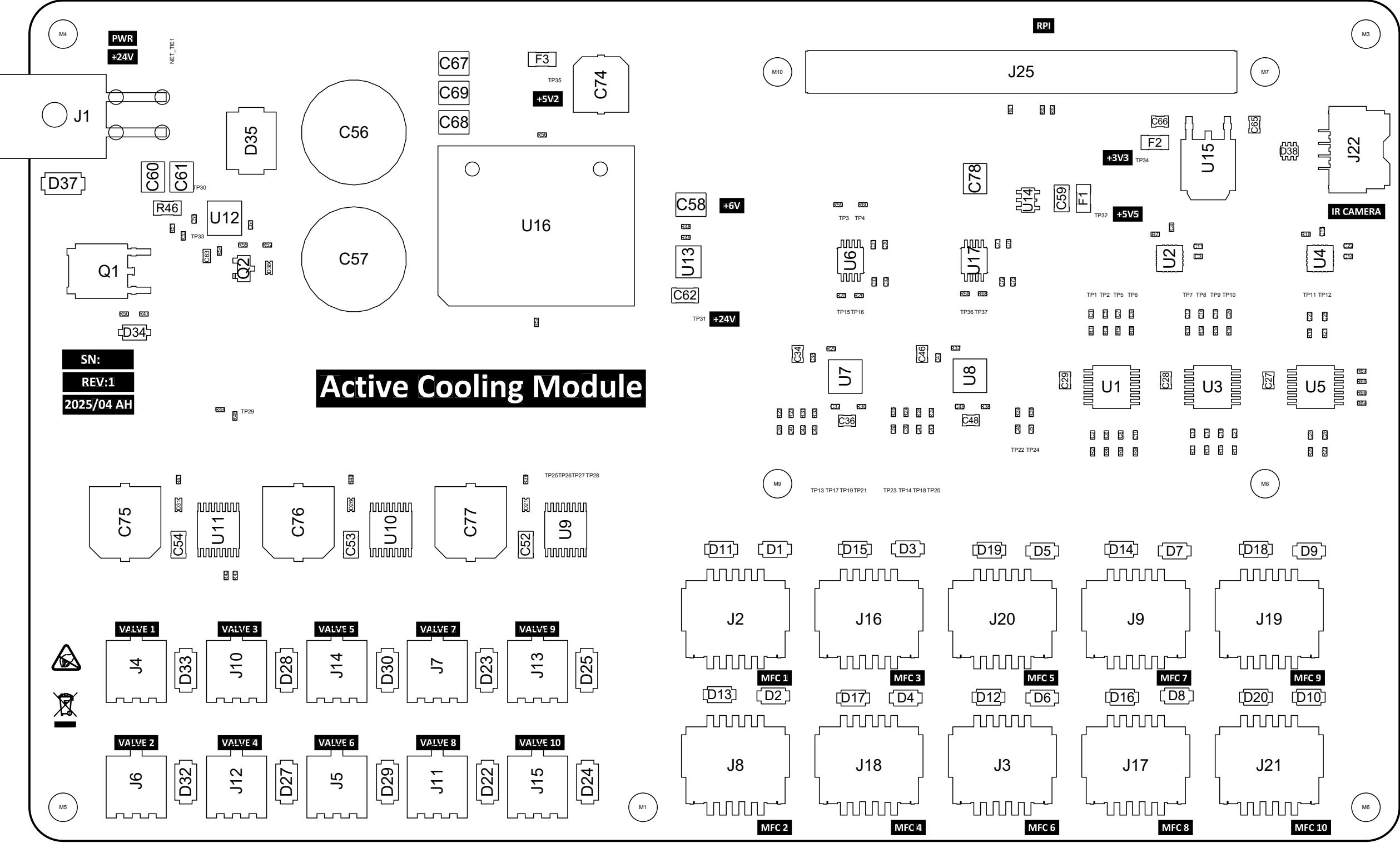


Drill Table				
Symbol	Count	Hole Size	Plated	Hole Tolerance
⊗	1	3.05	Non-Plated	
▼	4	1.85	Plated	
⊙	2	1.77	Plated	
✕	5	1.22	Plated	
▽	20	1.02	Non-Plated	
○	60	1.02	Plated	
⊕	4	1.10	Plated	
◇	9	3.50	Plated	
☆	182	0.40	Plated	
□	171	0.20	Plated	
☆	152	0.30	Plated	

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Assembly TOP

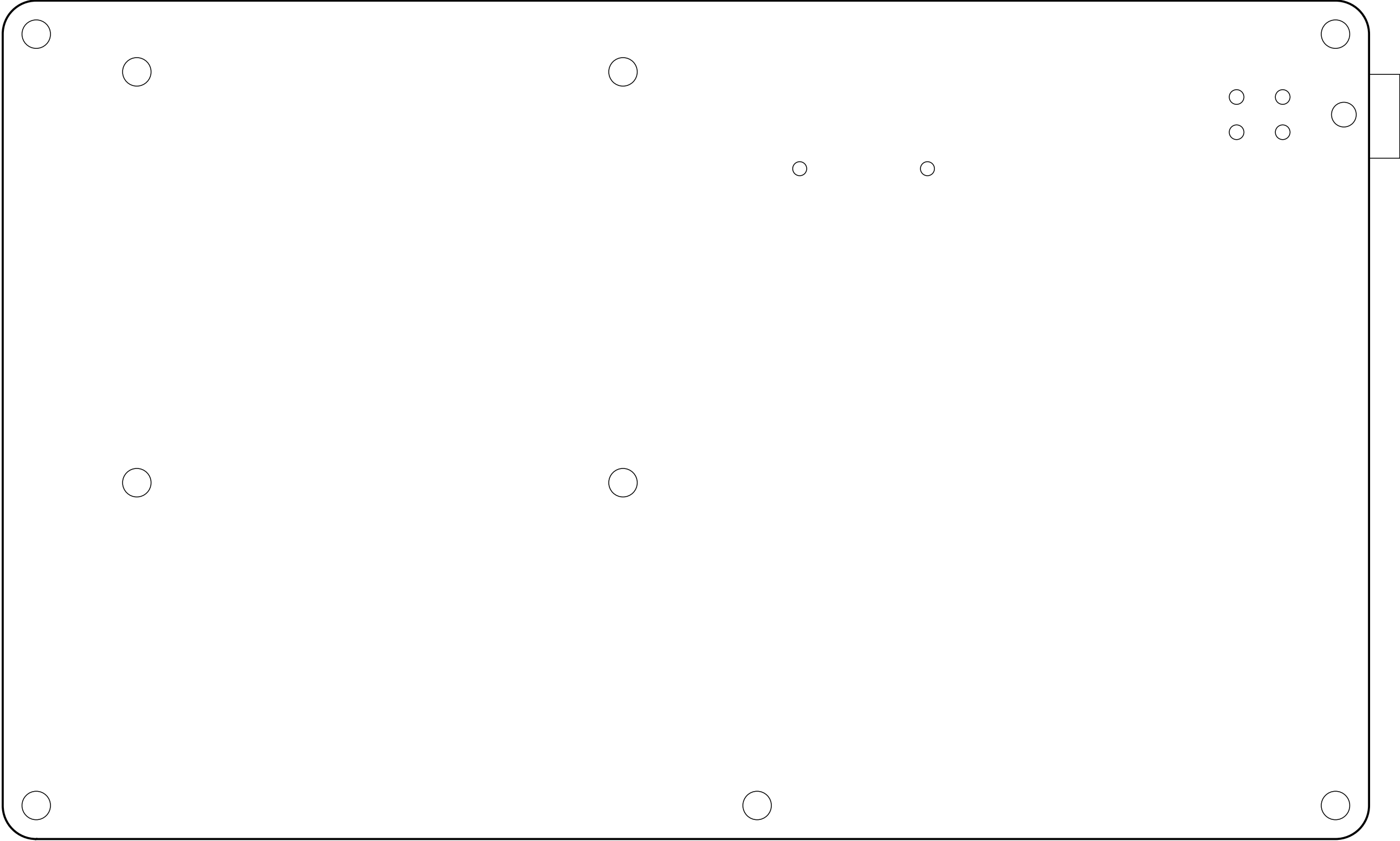
View from Top side (Scale 2:1)




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Assembly BOTTOM

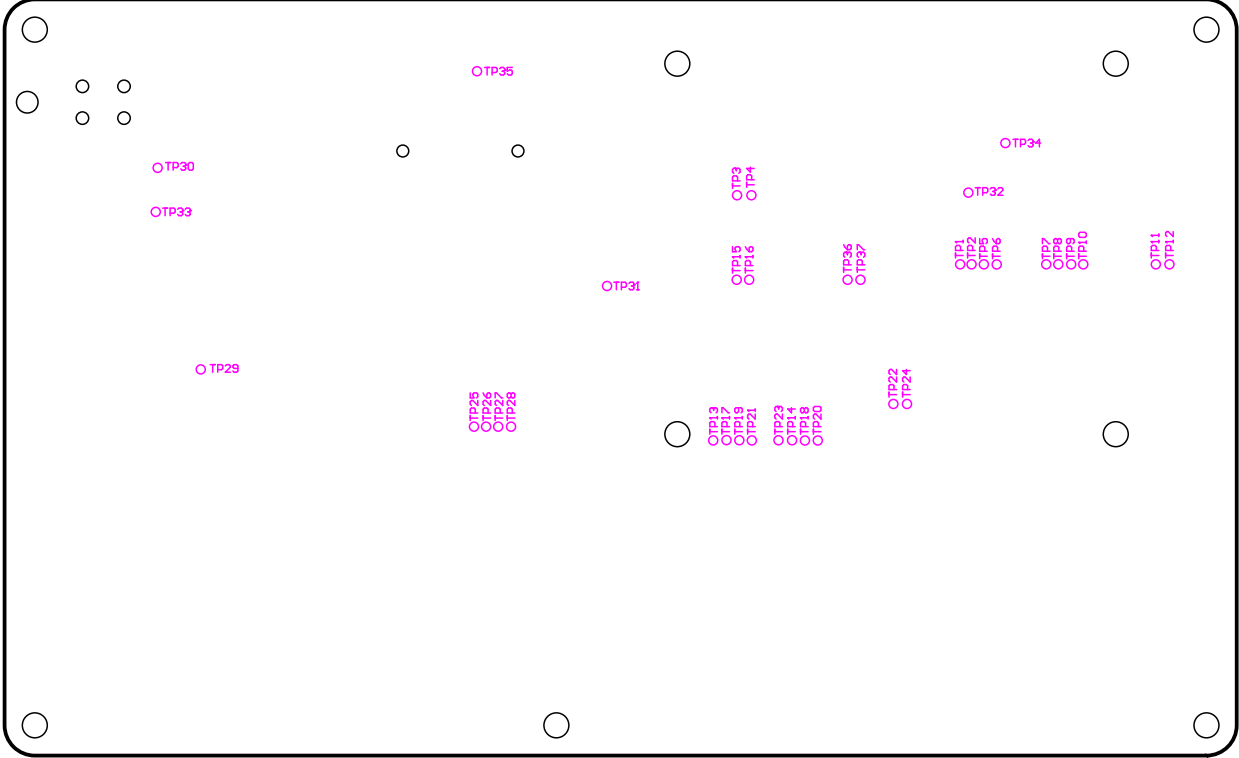
View from Bottom side (Scale 2:1)



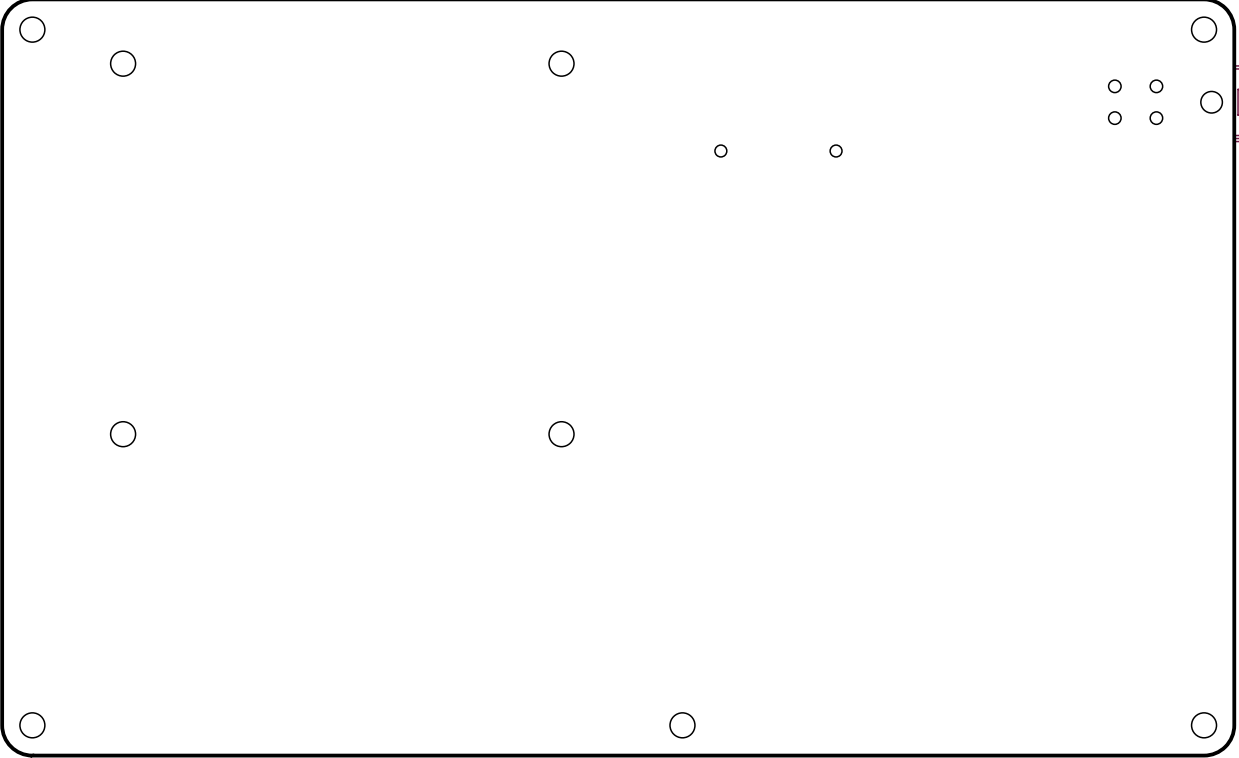
Revision 1	Project Name:Active_Cooling.PrjPcb	Project #:A1-023378-02
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TestPoints

View from Top side (Scale 1:1)



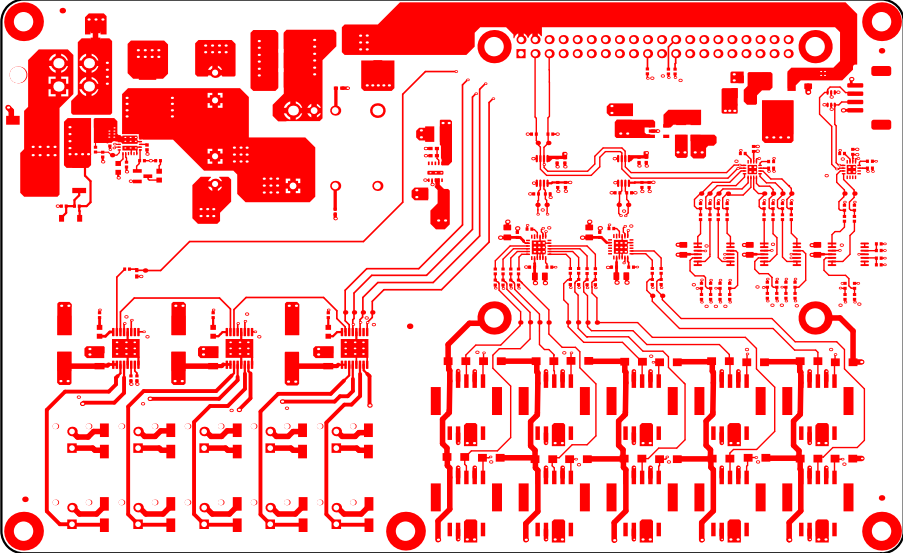
View from Bottom side (Scale 1:1)



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Fabrication Drawing

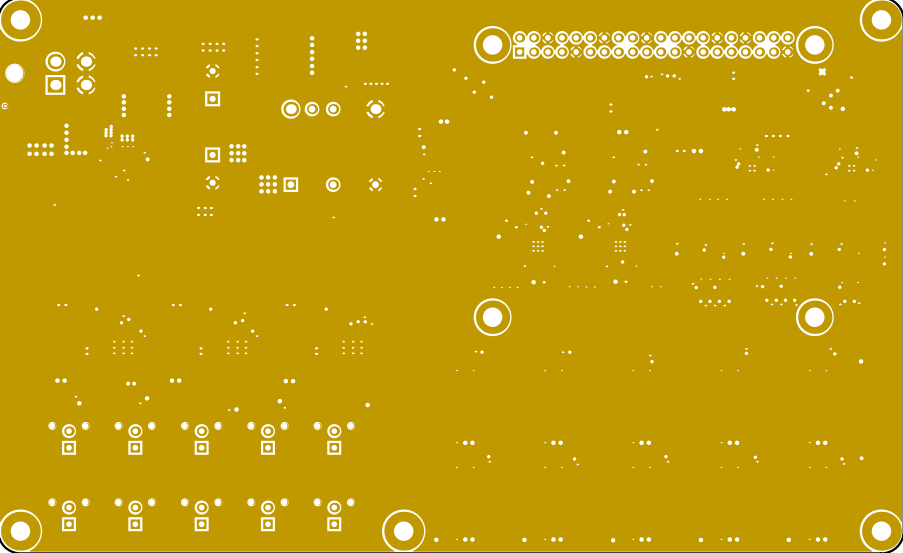
L1 (Scale: 1:1.37)



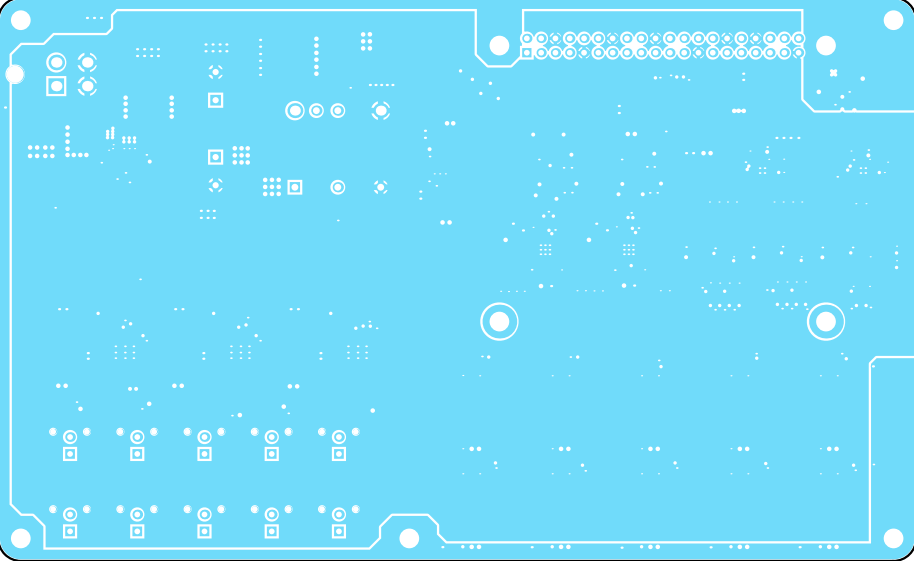
Note:

- 1 Minimum Spacing >0.2mm
- 2 Minimum Track >0.2mm
- 3 Minimum Through Hole VIA: 0.46mm (pad) / 0.2mm (drill). Drilling: L1-L8
- 4 REMOVE ALL NON-FUNCTIONAL INNER LAYER PADS.
- 5 FINISHED PANEL THICKNESS IS NOT CRITICAL: TO BE APPROXIMATELY 1.6mm
- 6 BOARD FINISH: IMMERSION Au/ELECTROLESS Ni; 0.05-0.12 um GOLD; 3-6um NICKEL
- 7 SOLDER RESIST: APPLY TO BOTH SIDES COLOUR - Green
- 8 COMPONENT IDENT: COLOUR TO BE WHITE
- 9 RECOMMENDED STACKUP SHOWN BELOW. ADJUSTMENT ARE ALLOWED BUT MUST BE CONFIRMED WITH CLIENT

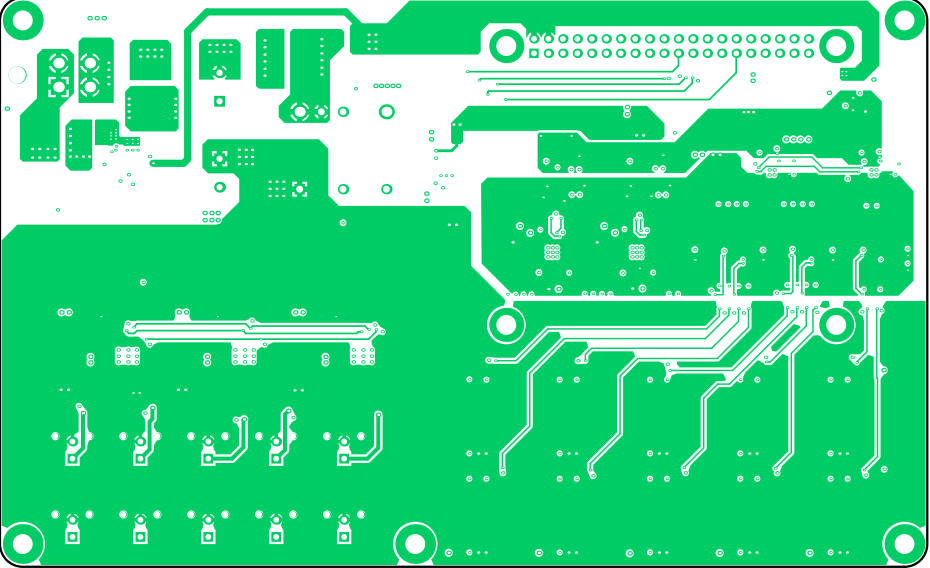
L2[GND] (Scale: 1:1.36)



L3[GND] (Scale: 1:1.34)



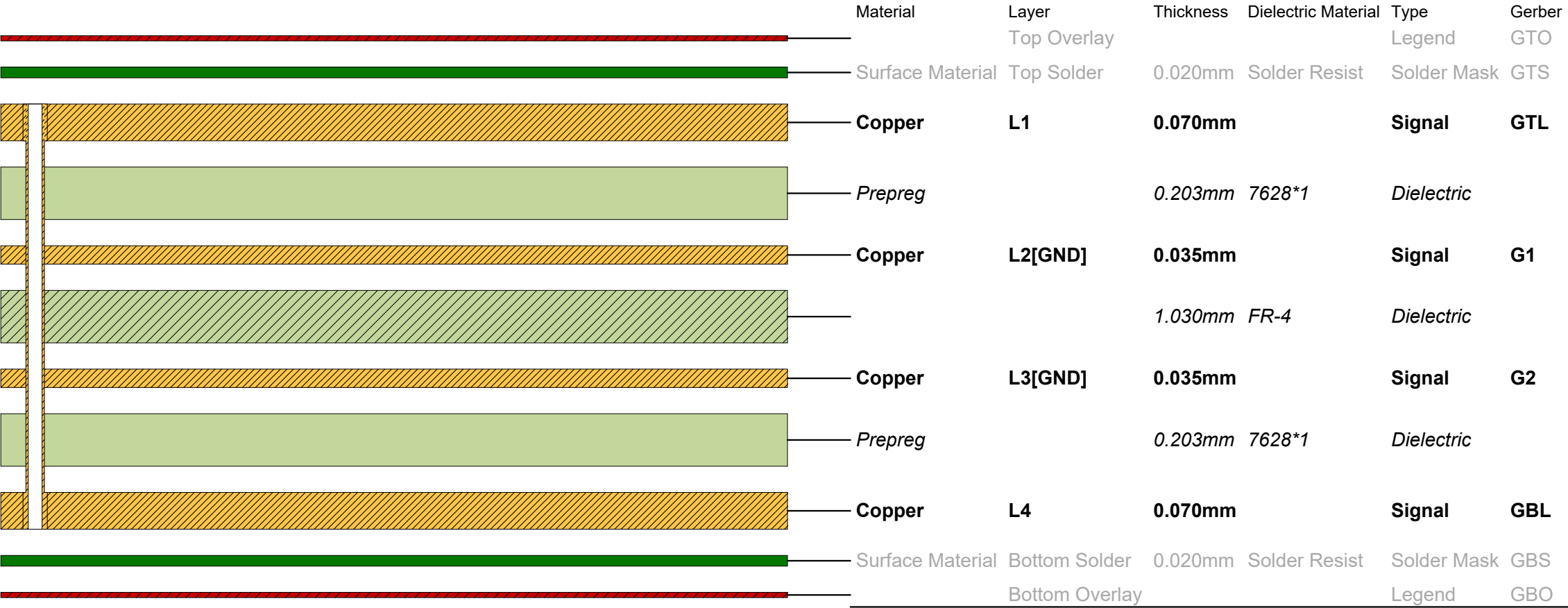
L4 (Scale: 1:1.33)



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STACKUP

Layer Stack Legend



Total thickness: 1.687mm

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